

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 2001302879 A

(43) Date of publication of application: 31.10.01

(51) Int. Cl

**C08L 63/00**  
**B32B 15/08**  
**C08G 59/62**  
**C08J 5/04**  
**C08K 5/49**  
**C08L 79/00**  
**H05K 1/03**

(21) Application number: 2000123496

(22) Date of filing: 25.04.00

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**(54) EPOXY RESIN COMPOSITION AND PREPREG  
AND PRINTED CIRCUIT BOARD USING THE  
SAME**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To obtain an epoxy resin composition capable of imparting good flame retardancy substantially without containing halogen atoms when forming an insulating layer by being supported to a sheetlike organic fibrous substrate.

**SOLUTION:** This epoxy resin composition comprises (A) an epoxy resin without containing a

halogen, (B) a phenolic resin, (C) a thermosetting resin having dihydrobenzoxazine ring, (D) a phosphorus compound and (E) an inorganic filler as essential components. The insulating layer is formed by impregnating the epoxy resin composition into an aramid fibrous substrate (preferably polyparaphenylene terephthalamide fibrous substrate) and supporting thereto. The component (B) is preferably a phenolic novolak resin containing phosphorus atom or nitrogen atom in the molecular structure thereof.

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